DW OR N PACKAGE

SDAS300 - MARCH 1995

- Bidirectional Bus Transceivers in High-Density 20-Pin Packages
- Choice of True or Inverting Logic
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic (N) 300-mil DIPs

DEVICE	LOGIC
SN74ALS641A, SN74AS641	True
SN74ALS642A	Inverting

(TOP VIEW) DIR 20 ∏ Vcc Α1 19 OE 2 А2 П 3 18**∏** B1 А3 П 17 **∏** B2 4 А4 Г 5 16 П вз A5 [15 **∏** B4 14 | B5 A6 [А7 Г 8 13**∏** B6 A8 **∏** 9 12 🛮 B7 GND 10 11 B8

description

These octal bus transceivers are designed for asynchronous two-way communication between

data buses. These devices transmit data from the A bus to the B bus or from the B bus to the A bus, depending upon the level at the direction-control (DIR) input. The output-enable (\overline{OE}) input disables the device so that the buses are effectively isolated.

The -1 versions of the SN74ALS641A and SN74ALS642A are identical to the standard versions, except that the recommended maximum I_{OL} is increased to 48 mA in the -1 versions.

The SN74ALS641A, SN74ALS642A, and SN74AS641 are characterized for operation from 0°C to 70°C.

FUNCTION TABLE

INP	UTS	OPERATION				
ŌE DIR		SN74ALS641A SN74AS641	SN74ALS642A			
L	L	B data to A bus	B data to A bus			
L H H X		A data to B bus	A data to B bus			
		Isolation	Isolation			

logic symbols†

SN74ALS641A, SN74AS641 19 OE G3 1 DIR 3 EN1 [BA] 3 EN2 [AB] 18 \triangleleft В1 \triangleright 2♀ 3 17 **A2 B2** 4 16 А3 **B3** 5 15 Α4 **B4** 6 14 Α5 **B5** 7 Α6 **B6** 12 8 **A7 B7** 9 11 **A8 B8**

SN74ALS642A 19 OE G3 1 DIR 3 EN1 [BA] 3 EN2 [AB] 18 В1 \triangleleft \triangleright 2 ♦ 17 **A2** B2 4 16 А3 **B3** 5 15 Α4 **B4** 6 14 Α5 **B5** 7 13 **B6** A6 8 12 **B7 A7** 9 11 В8 **A8**

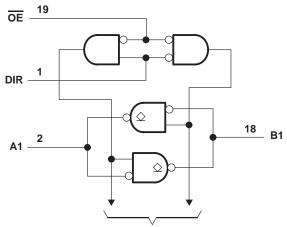
[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

TEXAS INSTRUMENTS

SDAS300 - MARCH 1995

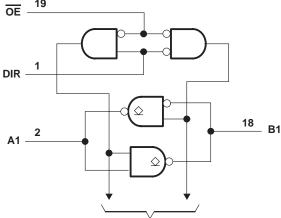
logic diagrams (positive logic)

SN74ALS641A, SN74AS641





SN74ALS642A



To Seven Other Transceivers

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}			V
Input voltage, V _I : All inputs and I/O ports			V
Operating free-air temperature range, TA:	SN74ALS641A, SN74ALS642A	0°C to 70°C	\mathbb{C}
Storage temperature range		65°C to 150°C	\mathbb{C}

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		_	'4ALS64 '4ALS64		UNIT
		MIN	NOM	MAX	
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
Vон	High-level output voltage			5.5	V
la.	Low-level output current			24	mA
lor	Low-level output current			48‡	IIIA
TA	Operating free-air temperature	0		70	°C

 $[\]ddagger$ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CO	TEST CONDITIONS				
				MIN	TYP [†]	MAX	
VIK		$V_{CC} = 4.5 \text{ V},$	$I_1 = -18 \text{ mA}$			-1.5	V
IOH		$V_{CC} = 4.5 \text{ V},$	V _{OH} = 5.5 V			0.1	mA
			I _{OL} = 12 mA		0.25	0.4	
VOL		$V_{CC} = 4.5 V$	I _{OL} = 24 mA		0.35	0.5	V
			$I_{OL} = 48 \text{ mA}^{\ddagger}$		0.35	0.5	
II	Control inputs	$V_{CC} = 5.5 V$,	V _I = 7 V			0.1	mA
1	Control inputs	V 55V	V. 27V			20	^
IН	Control inputs A or B ports§	$V_{CC} = 5.5 V,$	$V_1 = 2.7 \text{ V}$			20	μΑ
1	Control inputs	V 55V	V ₂ 0.4.V			-0.1	A
¹ı∟	A or B ports§	$V_{CC} = 5.5 V$	V _I = 0.4 V			-0.1	mA
	SN74ALS641A	V 55V	Outputs high		25	37	
	311/4AL3041A VCC = 5.5 V	V _{CC} = 5.5 V	Outputs low		33	47	A
ICC	CN74ALCC49A	V 55V	Outputs high		8	15	mA
	SN74ALS642A	V _{CC} = 5.5 V	Outputs low		18	28	

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _I	= 50 pF = 680 Ω = MIN t			UNIT
			MIN	MAX	MIN	MAX	
t _{PLH}	A D		5	25	10	30	
^t PHL	A or B	B or A	3	18	5	22	ns
t _{PLH}			8	30	10	30	
^t PHL	ŌĒ	A or B	8	30	15	38	ns
t _{PLH}	DIR	A or B	8	32	10	30	ns
tPHL	DIK	AUIB	8	32	15	38	115

[¶] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $[\]ddagger$ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V \$ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

SN74ALS641A, SN74ALS642A, SN74AS641 OCTAL BUS TRANSCEIVERS WITH OPEN-COLLECTOR OUTPUTS

SDAS300 - MARCH 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I : All inputs and I/O ports	7 V
Operating free-air temperature range, T _A : SN74AS641	0°C to 70°C
Storage temperature range	-65°C to 150°C

recommended operating conditions

		SI	SN74AS641		UNIT
		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
Vон	High-level output voltage			5.5	V
IOL	Low-level output current			64	mA
TA	Operating free-air temperature	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST 001	NDITIONS	SI	1		
		TEST COI	TEST CONDITIONS				UNIT
٧ıĸ		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2	V
loh		V _{CC} = 4.5 V,	V _{OH} = 5.5 V			0.1	mA
VOL		$V_{CC} = 4.5 V,$	I _{OL} = 64 mA		0.35	0.55	V
1.	Control inputs	Van EEV	V _I = 7 V			0.1	mA
1 ₁	A or B ports	V _{CC} = 5.5 V	V _I = 5.5 V			0.1	mA
I	Control inputs	Van EEV	V. 07V			20	
lιΗ	A or B ports§	V _{CC} = 5.5 V,	V _I = 2.7 V			70	μΑ
l	Control inputs	V	557			-0.5	mA
¹IL	A or B ports§	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.75	IIIA
loo		V00 - 5 5 V	Outputs high		50	82	mA
ICC		V _{CC} = 5.5 V	Outputs low		84	136	IIIA

[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

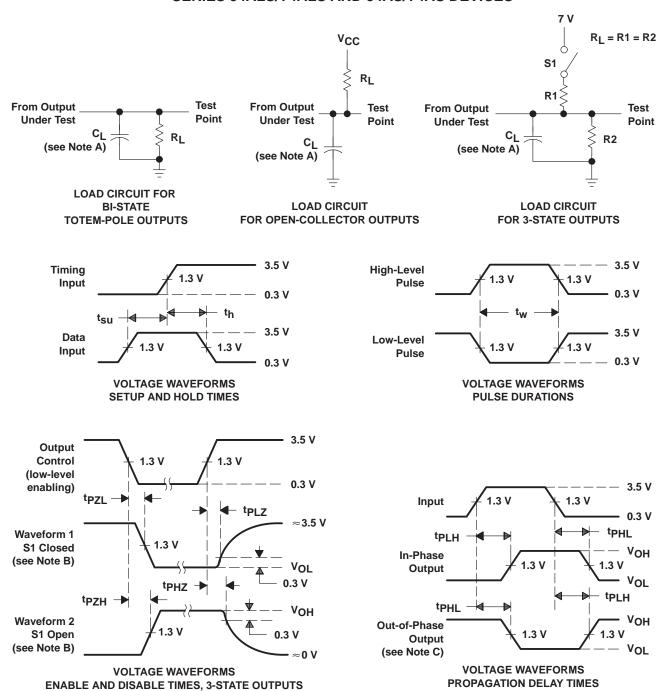
[§] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5^{\circ}$ $C_{L} = 50 \text{ pF}$ $R_{L} = 680 \Omega$ $T_{A} = \text{MIN to}$ $SN74A$, 2, 0 MAX†	UNIT
t _{PLH}	A or B	5 .	5	21	
t _{PHL}	A 01 B	B or A	1	7.5	ns
^t PLH	ŌĒ	A B	5	21	
t _{PHL}	OE .	A or B	1	9	ns
^t PLH	DIR	A or B	5	22	ns
^t PHL	DIK	AUID	1	10	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: $PRR \le 1$ MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms









PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ALS641A-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641A-1DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641A-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641A-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641A-1DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641A-1DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641A-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS641A-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS641A-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641A-1NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641A-1NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS641ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS641ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS641ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS642A-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS642A-1DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS642A-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM





.com 4-Jun-2007

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
SN74ALS642A-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS642A-1DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS642A-1DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS642A-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS642A-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS642A-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS642A-1NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS642A-1NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS642ADW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74ALS642ADWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74ALS642AN	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74AS641DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS641DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS641DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS641DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS641DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS641DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS641N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS641NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

 $^{(1)}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame



PACKAGE OPTION ADDENDUM

4-Jun-2007

retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

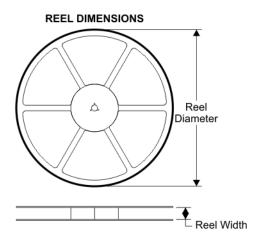
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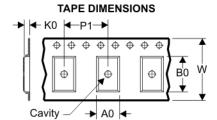
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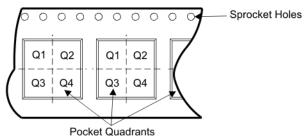
TAPE AND REEL BOX INFORMATION





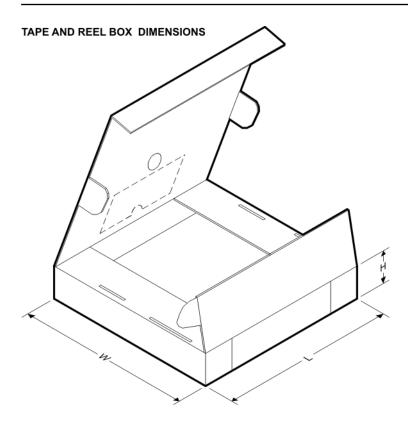
	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device	Package	Pins		Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS641A-1DWR	DW	20	SITE 41	330	24	10.8	13.0	2.7	12	24	Q1
SN74ALS641A-1NSR	NS	20	SITE 41	330	24	8.2	13.0	2.5	12	24	Q1
SN74ALS641ADWR	DW	20	SITE 41	330	24	10.8	13.0	2.7	12	24	Q1
SN74ALS641ANSR	NS	20	SITE 41	330	24	8.2	13.0	2.5	12	24	Q1
SN74ALS642A-1DWR	DW	20	SITE 41	330	24	10.8	13.0	2.7	12	24	Q1
SN74ALS642A-1NSR	NS	20	SITE 41	330	24	8.2	13.0	2.5	12	24	Q1
SN74AS641DWR	DW	20	SITE 41	330	24	10.8	13.0	2.7	12	24	Q1





Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)	
SN74ALS641A-1DWR	DW	20	SITE 41	346.0	346.0	41.0	
SN74ALS641A-1NSR	NS	20	SITE 41	346.0	346.0	41.0	
SN74ALS641ADWR	DW	20	SITE 41	346.0	346.0	41.0	
SN74ALS641ANSR	NS	20	SITE 41	346.0	346.0	41.0	
SN74ALS642A-1DWR	DW	20	SITE 41	346.0	346.0	41.0	
SN74ALS642A-1NSR	NS	20	SITE 41	346.0	346.0	41.0	
SN74AS641DWR	DW	20	SITE 41	346.0	346.0	41.0	

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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